

# 74AUP1G09

Low-power 2-input AND gate with open-drain

Rev. 4 — 28 June 2012

Product data sheet

## 1. General description

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The 74AUP1G09 provides the single 2-input AND gate with an open-drain output. The output of the device is an open-drain and can be connected to other open-drain outputs to implement active-LOW wired-OR or active-HIGH wired-AND functions.

Schmitt trigger action at all inputs makes the circuit tolerant to slower input rise and fall times across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device is fully specified for partial Power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

## 2. Features and benefits

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- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
  - ◆ JESD8-12 (0.8 V to 1.3 V)
  - ◆ JESD8-11 (0.9 V to 1.65 V)
  - ◆ JESD8-7 (1.2 V to 1.95 V)
  - ◆ JESD8-5 (1.8 V to 2.7 V)
  - ◆ JESD8-B (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F Class 3A exceeds 5000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
  - ◆ CDM JESD22-C101E exceeds 1000 V
- Low static power consumption;  $I_{CC} = 0.9 \mu\text{A}$  (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of  $V_{CC}$
- $I_{OFF}$  circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AUP1G09GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74AUP1G09GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74AUP1G09GF	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74AUP1G09GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74AUP1G09GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74AUP1G09GX	-40 °C to +125 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226

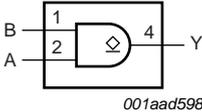
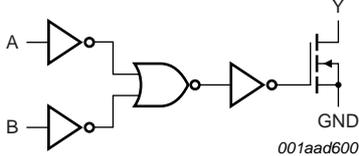
### 4. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74AUP1G09GW	p9
74AUP1G09GM	p9
74AUP1G09GF	p9
74AUP1G09GN	p9
74AUP1G09GS	p9
74AUP1G09GX	p9

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

### 5. Functional diagram

 <p>001aad598</p>	 <p>001aad599</p>	 <p>001aad600</p>
<b>Fig 1. Logic symbol</b>	<b>Fig 2. IEC logic symbol</b>	<b>Fig 3. Logic diagram</b>

## 6. Pinning information

### 6.1 Pinning

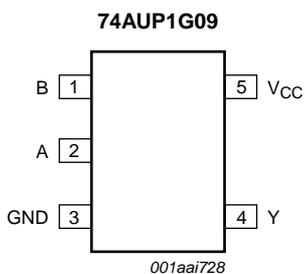


Fig 4. Pin configuration SOT353-1

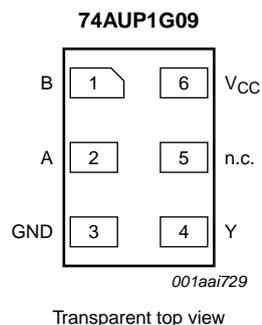


Fig 5. Pin configuration SOT886

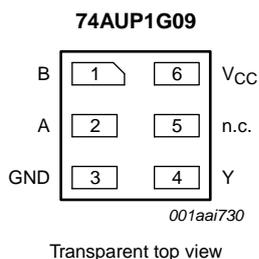


Fig 6. Pin configuration SOT891, SOT1115 and SOT1202

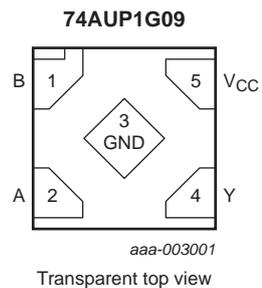


Fig 7. Pin configuration SOT1226 (X2SON5)

### 6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	TSSOP5 and X2SON5	XSON6	
B	1	1	data input
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	Z

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF state.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+4.6	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		<sup>[1]</sup> -0.5	+4.6	V
$I_{OK}$	output clamping current	$V_O < 0$ V	-50	-	mA
$V_O$	output voltage	Active mode and Power-down mode	<sup>[1]</sup> -0.5	+4.6	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	+20	mA
$I_{CC}$	supply current		-	+50	mA
$I_{GND}$	ground current		-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	<sup>[2]</sup> -	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP5 packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.

For XSON6 and X2SON5 packages: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		0.8	3.6	V
$V_I$	input voltage		0	3.6	V
$V_O$	output voltage	Active mode and Power-down mode	0	3.6	V
$T_{amb}$	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 0.8$ V to 3.6 V	0	200	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = 25 °C</b>						
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.7V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	0.65V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	0.3V <sub>CC</sub>	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	0.35V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.3V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.31	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.31	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.31	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.44	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.31	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.44	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.1	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 3.6 V	-	-	±0.1	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.2	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.2	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.5	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.3 V	-	-	40	μA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 0 V to 3.6 V; V <sub>I</sub> = GND or V <sub>CC</sub>	-	0.8	-	pF
C <sub>O</sub>	output capacitance	output enabled; V <sub>O</sub> = GND; V <sub>CC</sub> = 0 V	-	1.7	-	pF
		output disabled; V <sub>O</sub> = GND; V <sub>CC</sub> = 0 V	-	1.1	-	pF
<b>T<sub>amb</sub> = -40 °C to +85 °C</b>						
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.7V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	0.65V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	0.3V <sub>CC</sub>	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	0.35V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.3V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.37	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.35	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.33	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.45	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.33	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.45	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.5	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 3.6 V	-	-	±0.5	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.5	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.6	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.9	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.3 V	-	-	50	μA
<b>T<sub>amb</sub> = -40 °C to +125 °C</b>						
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.75V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	0.7V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	0.25V <sub>CC</sub>	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	0.3V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.11	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.33V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.41	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.39	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.36	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.50	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.50	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.75	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 3.6 V	-	-	±0.75	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.75	μA

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\Delta I_{OFF}$	additional power-off leakage current	$V_I$ or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	$\pm 0.75$	$\mu A$
$I_{CC}$	supply current	$V_I = GND$ or $V_{CC}$ ; $I_O = 0$ A; $V_{CC} = 0.8$ V to 3.6 V	-	-	1.4	$\mu A$
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 0.6$ V; $I_O = 0$ A; $V_{CC} = 3.3$ V	-	-	75	$\mu A$

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V; for test circuit see [Figure 9](#))

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C			Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max (85 °C)	Max (125 °C)	

**$C_L = 5$  pF**

$t_{pd}$	propagation delay	A or B to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>							
		$V_{CC} = 0.8$ V	-	13.5	-	-	-	-	ns
		$V_{CC} = 1.1$ V to 1.3 V	1.9	4.6	10.4	1.8	11.4	12.6	ns
		$V_{CC} = 1.4$ V to 1.6 V	1.5	3.3	6.5	1.4	7.4	8.2	ns
		$V_{CC} = 1.65$ V to 1.95 V	1.2	2.9	5.1	1.1	5.9	6.5	ns
		$V_{CC} = 2.3$ V to 2.7 V	1.0	2.2	3.8	0.9	4.5	4.9	ns
		$V_{CC} = 3.0$ V to 3.6 V	0.9	2.3	4.0	0.8	4.5	4.9	ns

**$C_L = 10$  pF**

$t_{pd}$	propagation delay	A or B to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>							
		$V_{CC} = 0.8$ V	-	16.3	-	-	-	-	ns
		$V_{CC} = 1.1$ V to 1.3 V	2.3	5.6	12.3	2.1	13.7	15.1	ns
		$V_{CC} = 1.4$ V to 1.6 V	1.8	4.1	7.6	1.7	8.8	9.7	ns
		$V_{CC} = 1.65$ V to 1.95 V	1.6	3.8	6.1	1.4	7.1	7.8	ns
		$V_{CC} = 2.3$ V to 2.7 V	1.4	2.9	4.6	1.2	5.4	5.9	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.3	3.2	5.7	1.1	6.4	7.0	ns

**$C_L = 15$  pF**

$t_{pd}$	propagation delay	A or B to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>							
		$V_{CC} = 0.8$ V	-	19.0	-	-	-	-	ns
		$V_{CC} = 1.1$ V to 1.3 V	2.6	6.6	14.2	2.4	15.8	17.4	ns
		$V_{CC} = 1.4$ V to 1.6 V	2.1	4.8	8.7	1.9	10.1	11.1	ns
		$V_{CC} = 1.65$ V to 1.95 V	1.9	4.6	7.6	1.7	8.5	9.3	ns
		$V_{CC} = 2.3$ V to 2.7 V	1.6	3.6	5.6	1.5	6.3	6.9	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.6	4.1	7.5	1.4	8.3	9.1	ns

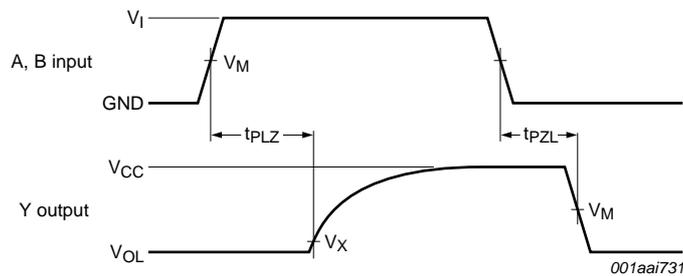
**$C_L = 30$  pF**

**Table 8. Dynamic characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V; for test circuit see [Figure 9](#))

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C			Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max (85 °C)	Max (125 °C)	
$t_{pd}$	propagation delay	A or B to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>							
		$V_{CC} = 0.8\text{ V}$	-	27.0	-	-	-	-	ns
		$V_{CC} = 1.1\text{ V to }1.3\text{ V}$	3.6	9.5	19.5	3.2	21.8	24.0	ns
		$V_{CC} = 1.4\text{ V to }1.6\text{ V}$	2.9	7.0	11.5	2.6	13.6	15.0	ns
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	2.6	7.0	12.1	2.3	13.3	14.6	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2.4	5.4	8.9	2.1	9.9	10.9	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	2.3	6.5	12.7	2.1	13.9	15.3	ns
<b><math>C_L = 5\text{ pF}, 10\text{ pF}, 15\text{ pF}</math> and <math>30\text{ pF}</math></b>									
$C_{PD}$	power dissipation capacitance	$f_i = 1\text{ MHz};$ <sup>[3]</sup> $V_i = \text{GND to }V_{CC}$							
		$V_{CC} = 0.8\text{ V}$	-	0.6	-	-	-	-	pF
		$V_{CC} = 1.1\text{ V to }1.3\text{ V}$	-	0.7	-	-	-	-	pF
		$V_{CC} = 1.4\text{ V to }1.6\text{ V}$	-	0.8	-	-	-	-	pF
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	0.9	-	-	-	-	pF
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	1.1	-	-	-	-	pF
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	1.4	-	-	-	pF	

- [1] All typical values are measured at nominal  $V_{CC}$ .
- [2]  $t_{pd}$  is the same as  $t_{pZL}$  and  $t_{PLZ}$ .
- [3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N$  where:  
 $f_i$  = input frequency in MHz;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching.

## 12. Waveforms

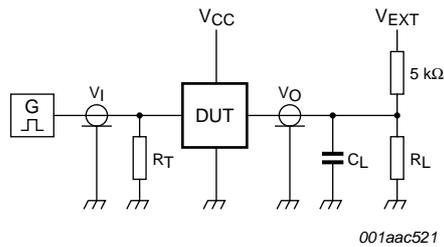


Measurement points are given in [Table 9](#).  
 $V_{OL}$  is a typical output voltage level that occurs with the output load.

**Fig 8. The data input (A or B) to output (Y) propagation delays**

Table 9. Measurement points

Supply voltage	Input	Output	
$V_{CC}$	$V_M$	$V_M$	$V_X$
0.8 V to 1.6 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.1 V$
1.65 V to 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15 V$
3.0 V to 3.6 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.3 V$



Test data is given in [Table 10](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

Fig 9. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Load		$V_{EXT}$		
$V_{CC}$	$C_L$	$R_L$ [1]	$t_{PLH}$ , $t_{PHL}$	$t_{PZH}$ , $t_{PHZ}$	$t_{PZL}$ , $t_{PLZ}$
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	$2V_{CC}$

[1] For measuring enable and disable times  $R_L = 5 k\Omega$ .

For measuring propagation delays, set-up and hold times, and pulse width,  $R_L = 1 M\Omega$ .

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

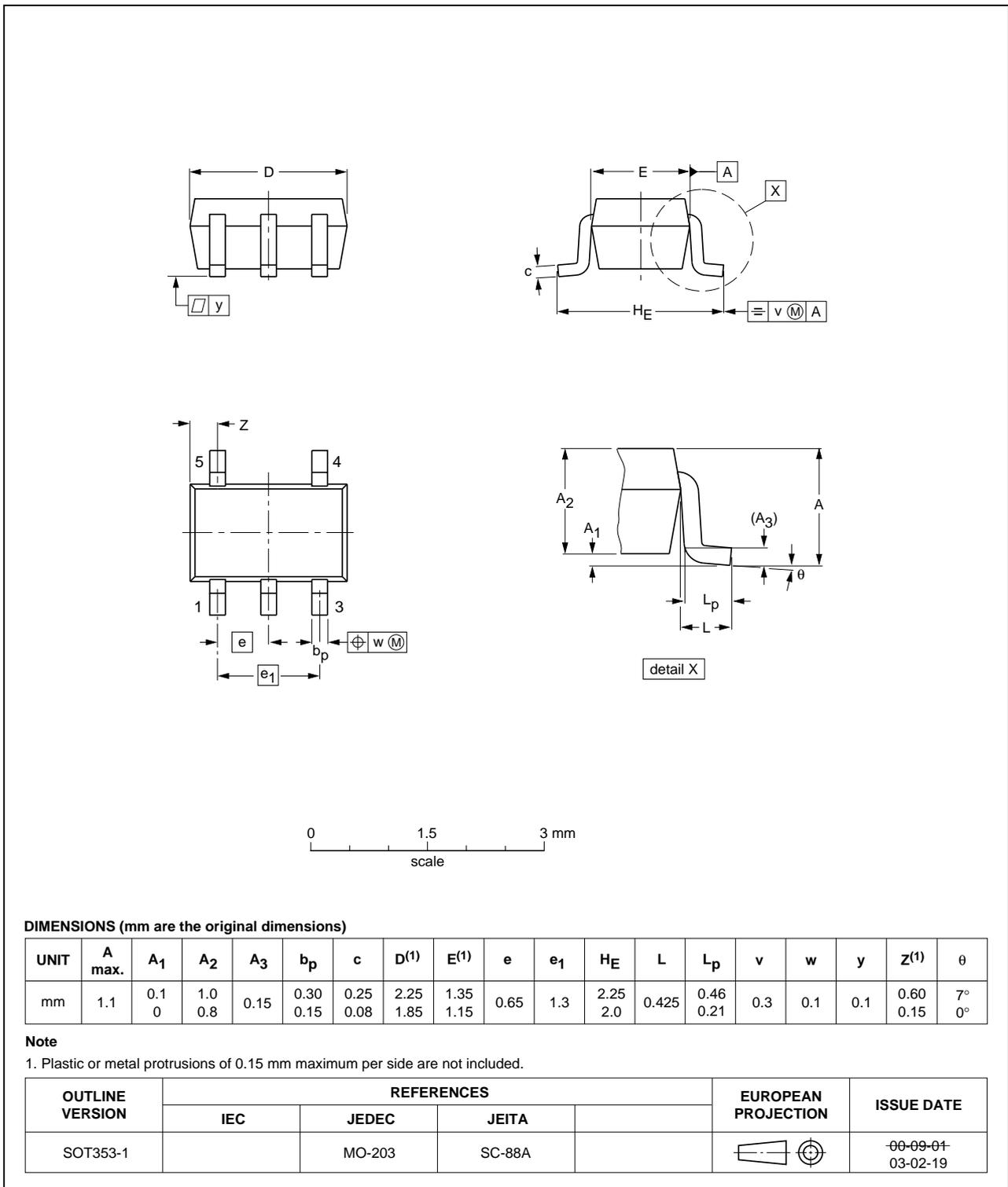


Fig 10. Package outline SOT353-1 (TSSOP5)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

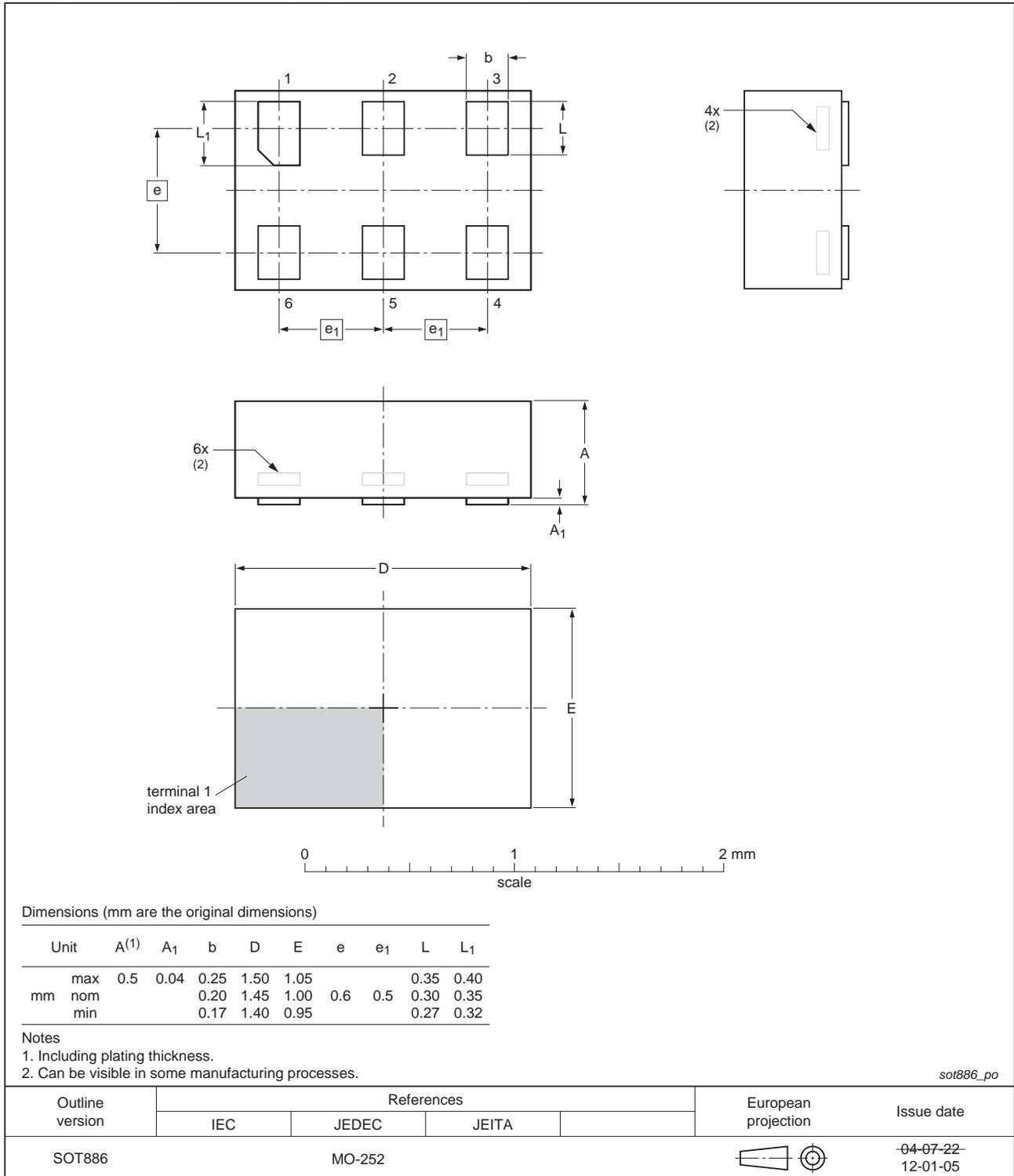


Fig 11. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

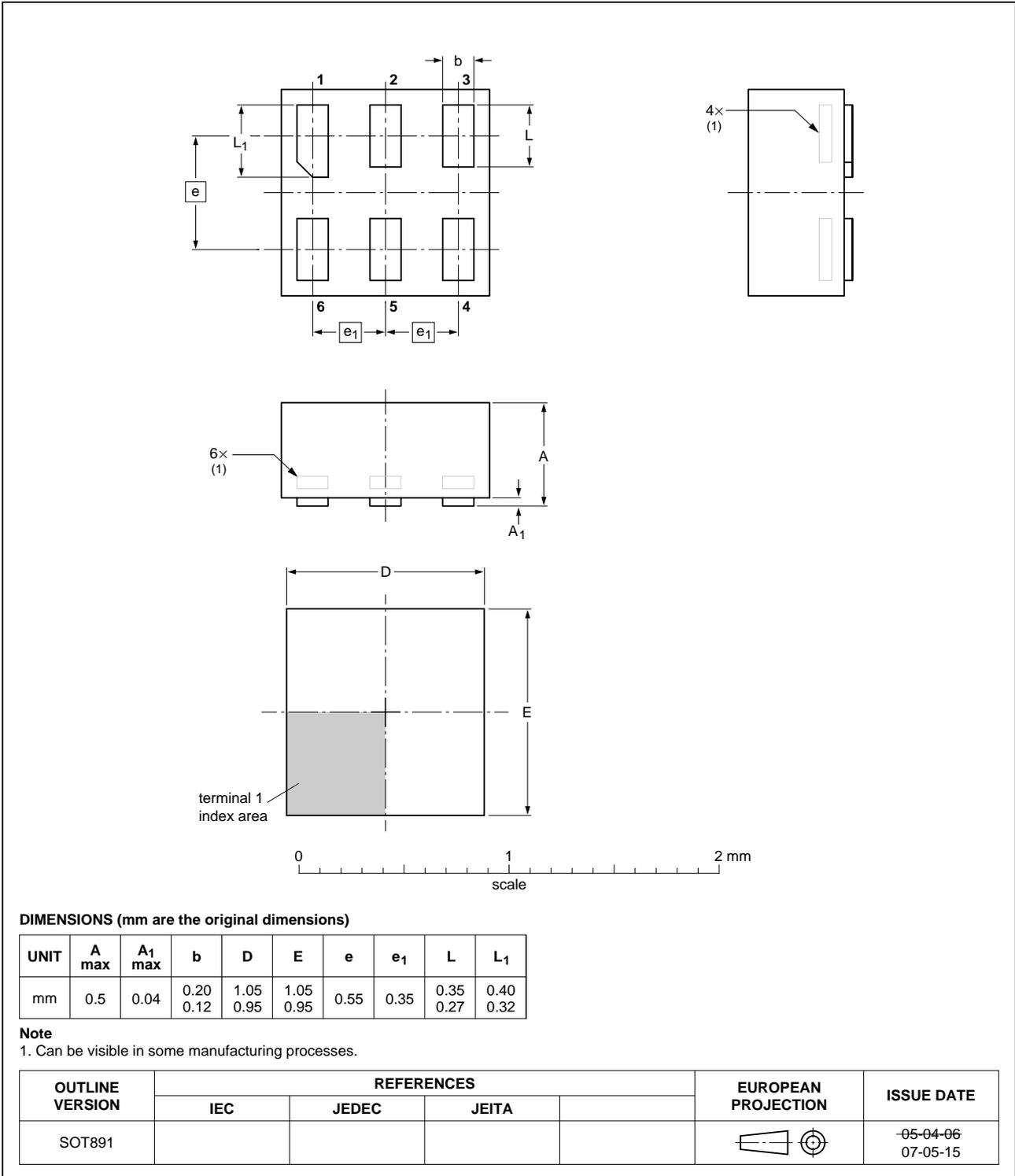


Fig 12. Package outline SOT891 (XSON6)

**XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm**

SOT1115

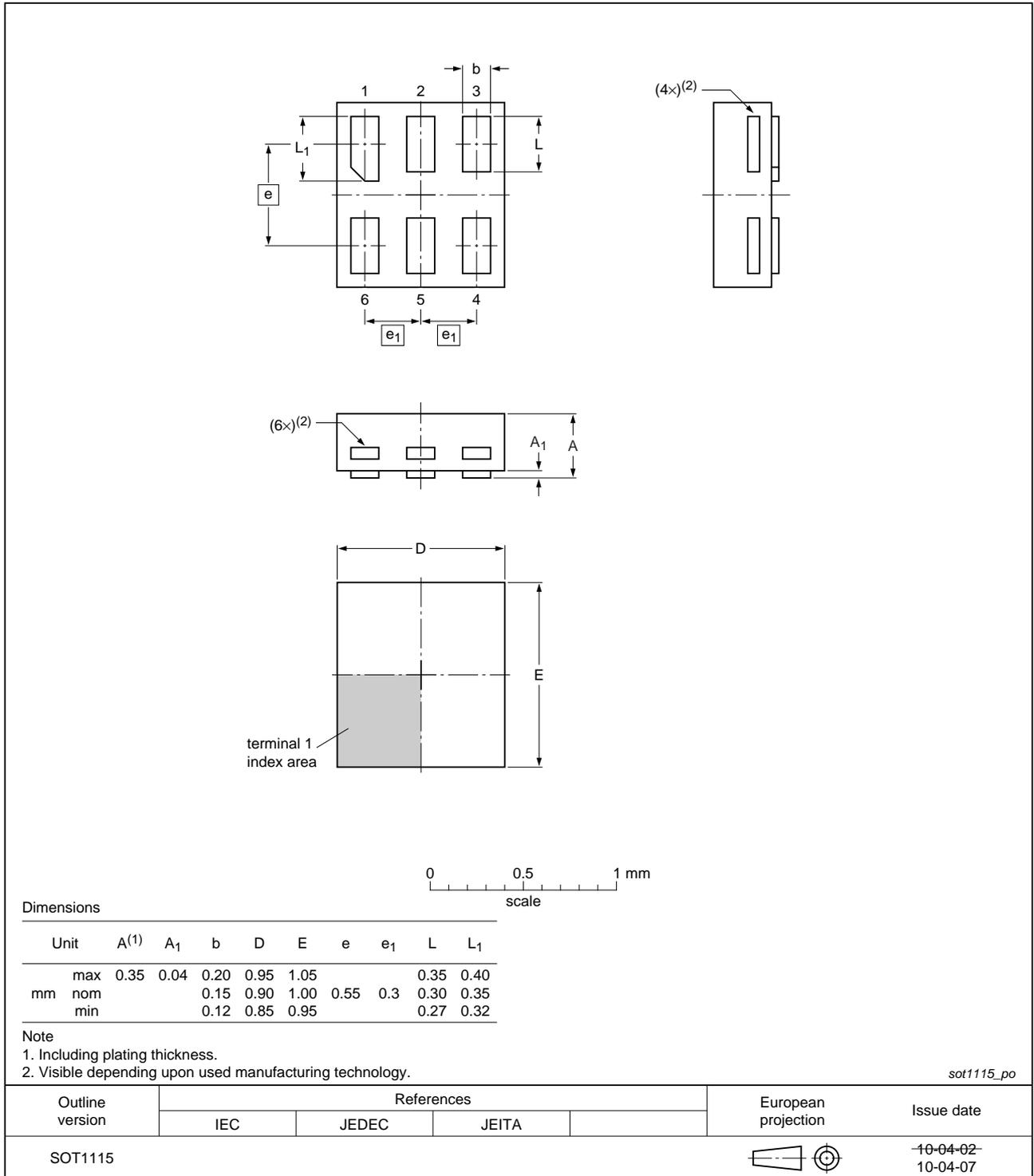
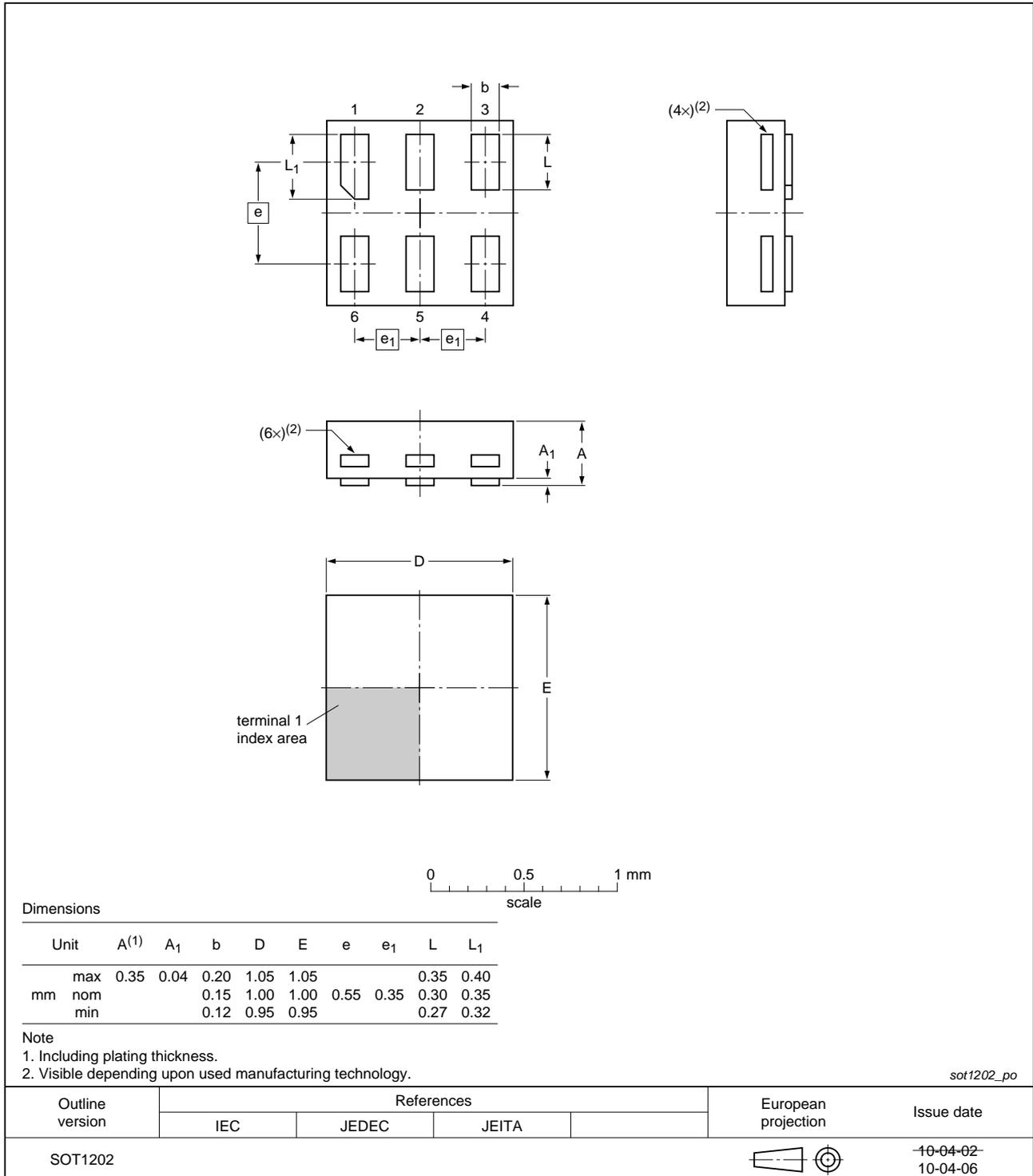


Fig 13. Package outline SOT1115 (XSON6)

**XSON6: extremely thin small outline package; no leads;  
6 terminals; body 1.0 x 1.0 x 0.35 mm**

**SOT1202**



**Fig 14. Package outline SOT1202 (XSON6)**

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;  
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

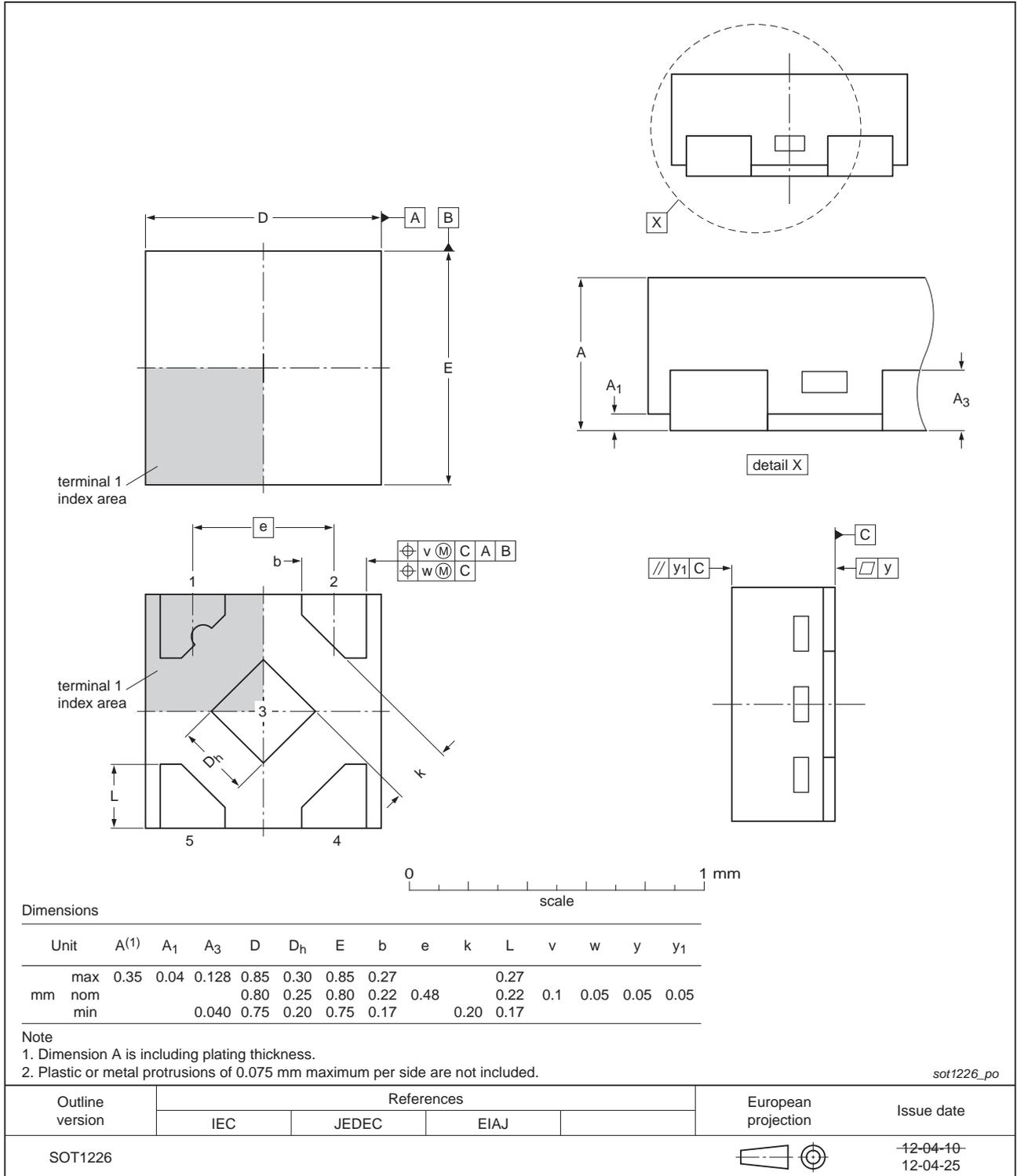


Fig 15. Package outline SOT1226 (X2SON5)

## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1G09 v.4	20120628	Product data sheet	-	74AUP1G09 v.3
Modifications:	<ul style="list-style-type: none"><li>Added type number 74AUP1G09GX (SOT1226)</li><li>Package outline drawing of SOT886 (<a href="#">Figure 11</a>) modified.</li></ul>			
74AUP1G09 v.3	20111128	Product data sheet	-	74AUP1G09 v.2
Modifications:	<ul style="list-style-type: none"><li>Legal pages updated.</li></ul>			
74AUP1G09 v.2	20100709	Product data sheet	-	74AUP1G09 v.1
74AUP1G09 v.1	20090115	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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